Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (Original): An imaging apparatus comprising:

a semiconductor imaging device which converts incident light to an electrical signal;

an optical filter which is opposed to an incident surface of said semiconductor imaging device and transmits light of a certain wavelength; and

a fixing member fixing said optical filter by means of adhesion using a filler-containing adhesive;

wherein a diameter of said filler is smaller than or equal to a pixel size of said semiconductor imaging device.

Claim 2 (Original): The imaging apparatus according to claim 1, wherein said fixing member is a three-dimensional substrate.

Claim 3 (Original): An imaging apparatus comprising:

a semiconductor imaging device which converts incident light to an electrical signal; and

a substrate fixing said semiconductor imaging device by means of adhesion using a filler-containing adhesive;

wherein a diameter of said filler is smaller than or equal to a pixel size of said semiconductor imaging device.

Claim 4 (Original): The imaging apparatus according to claim 1 or 3, wherein said diameter of said filler is larger than or equal to 1/2 of a pixel size of said semiconductor imaging device.

Claim 5 (Original): The imaging apparatus according to claim 1 or 3, wherein said filler is spherical in shape.

Claim 6 (New): The imagining apparatus according to claim 1 or 3, wherein said diameter of said filler is smaller than or equal to 3.8 μm.

Claim 7 (New): A method of manufacturing an imaging apparatus comprising the steps of:

providing a substrate;

providing a semiconductor imaging device which converts incident light to an electrical signal, wherein the semiconductor imaging device has a pixel size;

mounting the semiconductor imaging device to the substrate;

providing an optical filter which transmits light of a certain wavelength;

selecting a filler-containing adhesive based on a diameter of the filler being smaller than or equal to the pixel size; and

mounting the optical filter to the substrate by means of adhesion using the filler-containing adhesive.

Claim 8 (New): The method of claim 8, wherein the diameter of the filler is larger than or equal to 1/2 of the pixel size.

Claim 9 (New): The method of claim 8, wherein the filler is spherical in shape.

Claim 10 (New): The method of claim 8, wherein the diameter of the filler is smaller than or equal to 3.8 μm.

Claim 11 (New): A method of manufacturing an imaging apparatus comprising the steps of:

providing a substrate;

providing an optical filter which transmits light of a certain wavelength;

mounting the optical filter to the substrate;

providing a semiconductor imaging device which converts incident light to an electrical signal, wherein the semiconductor imaging device has a pixel size;

selecting a filler-containing adhesive based on a diameter of the filler being smaller than or equal to the pixel size; and

mounting the semiconductor imaging device to the substrate by means of adhesion using the filler-containing adhesive.

Claim 12 (New): The method of claim 12, wherein the diameter of the filler is larger than or equal to 1/2 of the pixel size.

Claim 13 (New): The method of claim 11, wherein the filler is spherical in shape.

Claim 14 (New): The method of claim 11, wherein the diameter of the filler is smaller than or equal to 3.8 μm.